

IRF8113UTRPBF-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)		
30	0.004 at V _{GS} = 10 V	18	6.8 nC		
	0.005 at V _{GS} = 4.5 V	16	0.0110		

SO-8

Top View

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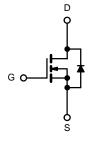
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FEATURES

- · Halogen-free
- Trench Power MOSFET
- Optimized for High-Side Synchronous Rectifier Operation
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- Notebook CPU Core
 - High-Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	S T _A = 25 °C, unles	s otherwise note	ed	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	
	T _C = 25 °C		18	
Continuous Proin Current (T. 450 °C)	T _C = 70 °C		16	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	15 ^{b, c}	
	T _A = 70 °C		13 ^{b, c}	_
Pulsed Drain Current		I _{DM}	50	A
Continuous Course David Diada Courset	T _C = 25 °C		3.8	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.1 ^{b, c}	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	22	
Avalanche Energy	L = 0.1 MH	E _{AS}	24	mJ
	T _C = 25 °C		4.5	
Mandagua Barra Birata atau	T _C = 70 °C		2.8	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{b, c}	W
	T _A = 70 °C		1.6 ^{b, c}	
Operating Junction and Storage Temperature Ra	T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	22	28	C/VV	

Notes:

- a. Base on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 °C/W.



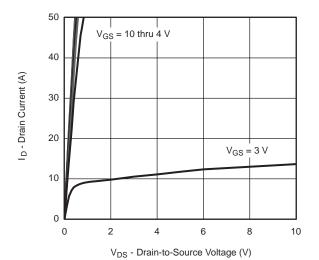
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static	1 1			, ,,		<u> </u>	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250A		28		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
	_	V _{GS} = 10 V, I _D = 11 A	0.004				
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		0.005		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 11 A		52		S	
Dynamic ^b	<u> </u>			1			
Input Capacitance	C _{iss}			820		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		195			
Reverse Transfer Capacitance	C _{rss}			73			
Tatal Cata Charma		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 11 A		15	23	nC	
Total Gate Charge	Q _g			6.8	10.2		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 11 \text{ A}$		2.5			
Gate-Drain Charge	Q _{gd}			2.3			
Gate Resistance	R _g	f = 1 MHz	0.36	1.8	3.6	Ω	
Turn-On Delay Time	t _{d(on)}			16	24		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.4 Ω		12	18		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 9 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		16	24		
Fall Time	t _f			10	20	ns	
Turn-On Delay Time	t _{d(on)}			8	16	113	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.4 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 9 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	24		
Fall Time	t _f			8	15		
Drain-Source Body Diode Characteris	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			25	Α	
Pulse Diode Forward Current ^a	I _{SM}				50		
Body Diode Voltage	V _{SD}	I _S = 9 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	30	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 9 A, dl/dt = 100 A/μs, T _J = 25 °C		6	12	nC	
Reverse Recovery Fall Time	t _a	i _F = 0 Λ, αιναι = 100 Λ/μο, 1 _J = 20 0		8		nc	
everse Recovery Rise Time t _b				7		ns	

Notes:

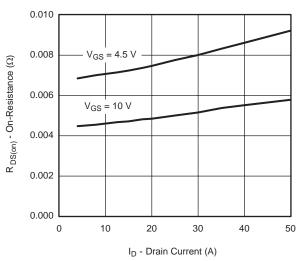
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

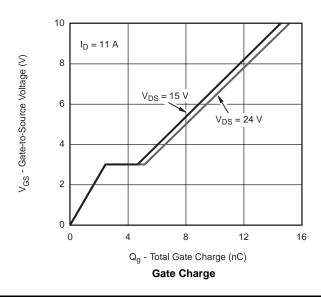




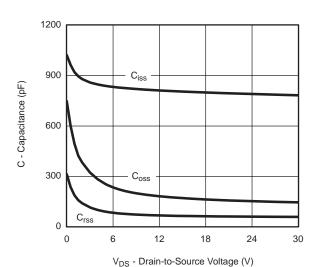
Output Characteristics



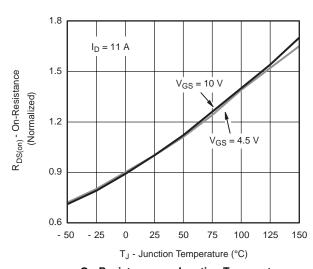
On-Resistance vs. Drain Current and Gate Voltage



V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**

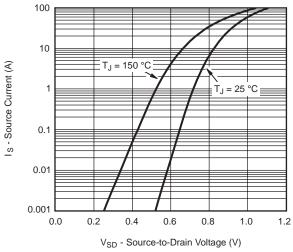


Capacitance

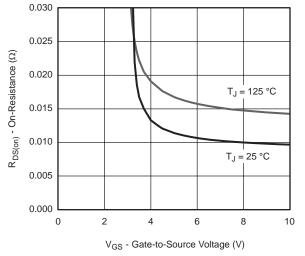


On-Resistance vs. Junction Temperature

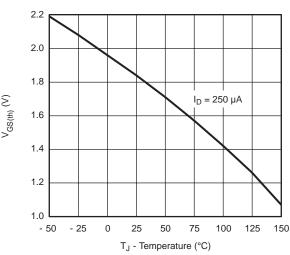




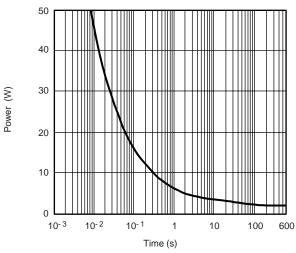




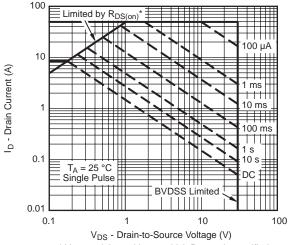
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



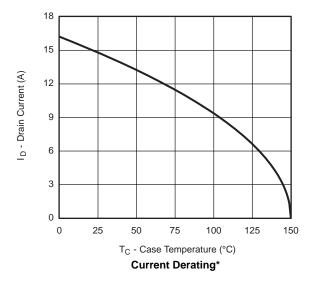
Single Pulse Power, Junction-to-Ambient

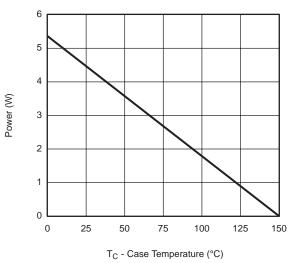


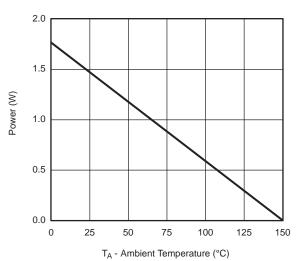
* $V_{GS} > \mbox{minimum} \ V_{GS}$ at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient







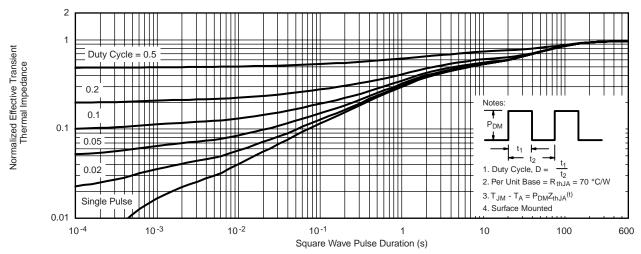


Power Derating, Junction-to-Foot

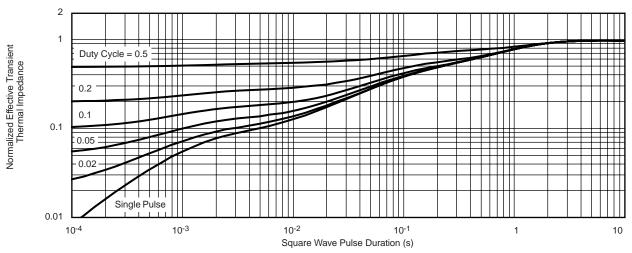
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







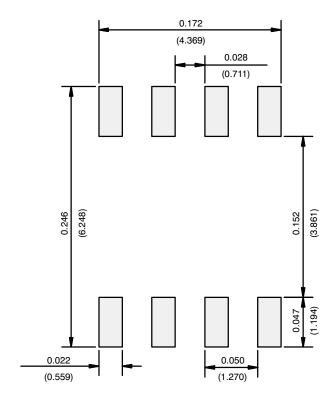
	MILLIN	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Pey I 11-Sep-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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